

**ECE414/514**  
**Electronics Packaging**  
**Spring 2012 Lecture 7**  
**Electrical E**  
**Electromagnetism & Modeling**

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**Portland State University**

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## Lecture topics

- SPICE review
- Worked transmission line example
- Electromagnetic waves on lines
- Electromagnetic modeling

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# Objectives

- Familiarize the student with SPICE
  - Note: Microsim (OrCad) PSPICE used below
  - LT-Spice available in the labs (Dept standard)
  - Use any equivalent program you choose
- Provide the skills to work simple examples
- Introduce basic concepts of TE, TM, and TEM waves on lines
- Present selected results of advanced electromagnetic modeling

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## 1. Getting started with SPICE

- Download any free limited capability version of SPICE
  - e.g. [www.5spice.com](http://www.5spice.com) or [www.winportal.com](http://www.winportal.com) or [www.beigebag.com](http://www.beigebag.com) or [www.orcad.com](http://www.orcad.com) (for OrCAD PCB Designer Lite DVD or download), etc
  - Or download LT-Spice, [www.linear.com/designtools/software/](http://www.linear.com/designtools/software/)
  - or find LTSpice in the labs
- Install it according to instructions and normal procedures
  - See Hambley “Electrical Engineering” (Pearson/Prentice-Hall) for OrCAD tutorial (applies to others) or any of many SPICE tutorial books
- In your Program library, find “Schematics.”
  - Explore the window, e.g. the zoom, and position controls bottom and right, etc.

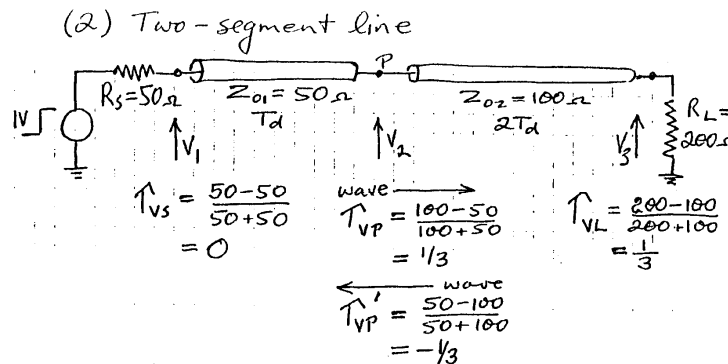
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## Example

- We will use the “bounce diagram” example from the reflections lecture (Electrical C)
- Step input to 50 ohm line  $T_d$  delay, then into a 100 ohm line of  $2T_d$  delay, terminated in 200 ohms.
- We will use only the Edit, Draw, and Analysis menu boxes, and the V probe below.



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- Draw circuit: Go to Draw, then to Place Part
  - There are different ways to get and place parts.
  - The easiest is to use the menu at the top right, but this contains parts you have used before, so starting off, you may need to go to Get New Part, OR Libraries (usually analog.slb here).
  - If we want a resistor, type R\* in the box.
  - A range of components is selected. Click on R.
  - Use Place, or Place and Close, or Click on R in the top right menu box. All bring you to:---->
  - A symbol of the resistor is now attached to the cursor.
  - Drag it to the right place, and left click
  - It will be positioned, but another symbol is now being dragged, for positioning another.
  - We only want one R, so right click to close.

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- Rotate
  - The resistor is horizontal; we want it vertical
  - We have to “select” the device
  - Draw a box around it with the left button
  - Color changes if successful
  - Go to Edit and select Rotate
  - Click away from device to de-select
  - Can drag device when “selected”
- Transmission lines, ground & source
  - Repeat for the lines (T), but now we want two
  - Repeat to place a ground (GND\_EARTH)
  - You need THREE grounds for this circuit
  - At the load, at the source, AND where the “common” line connections meet
- Use Vpulse for the source

- Wiring
  - In Draw, select Wire
  - This gives you a pencil to draw connections
  - Move the pencil to close to one wire, and click
  - Move to next, and click again
  - Right click to turn the pencil off
- Attributes
  - Select the component you want to change from default values (sometimes tricky)
  - We specify component values with the Attributes button
  - Select the parameter to change
  - Type in the value
  - Save attribute
  - Do next

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- Values

- R=200
- T1 (at source): Z0=50 TD=10n
- T2 (to load): Z0=100 TD=20n
- Vpulse: V1=0 V2=1 (or anything)
- TD=0 TR=0.1n PW=500n
- The times are to make the line delay much greater than the input step risetime, and to get the falling edge out of the times of interest

- Voltage probes

- Use the mouse to click and drag the voltage probes from the menu bar to the points we want:
  - Source voltage
  - Mid-line voltage
  - Load resistor voltage
- We want all wrt ground, so no need to insert ref points<sup>9</sup>

- Analysis

- In the Analysis box:
  - Do Probe Set Up (Auto-run Probe)
  - In Set Up, set “Transient”
- Hit Simulate (in Analysis box, or the icon to the left.)
- Will show errors, or analysis run
- Close box; Probe will come up
- Probe may show no plots ---- no problem!

- Probe plots

- Under Plot:
  - Choose the X-axis range user defined (say 250ns=0.2microsecs)
- Under Trace:
  - Add trace
  - Select from the list (of all parameters stored from the transient analysis)
  - Convention is V(T1,A+) means input (A) “central” conductor of T1

# Tools

- Next slide shows output
- Copy to Clipboard if necessary, using Tools

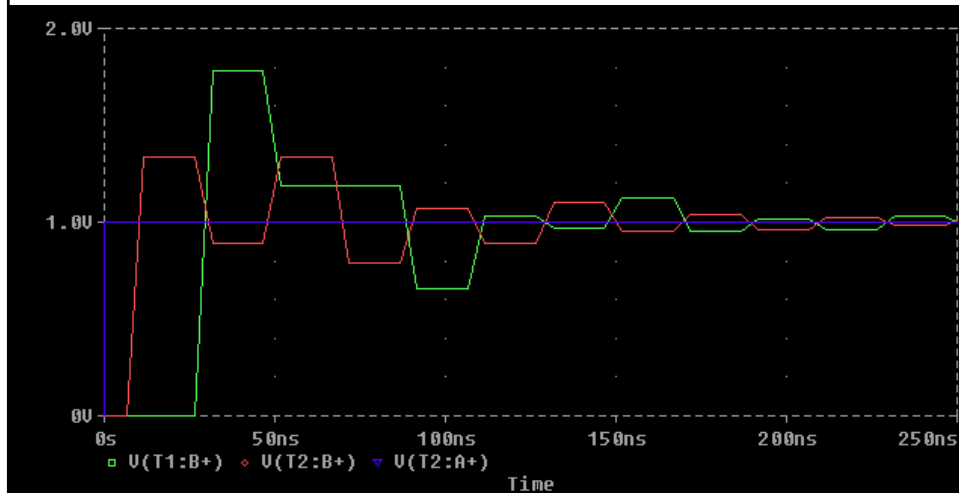
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# Probe output

Copy to Clipboard if necessary, using Tools

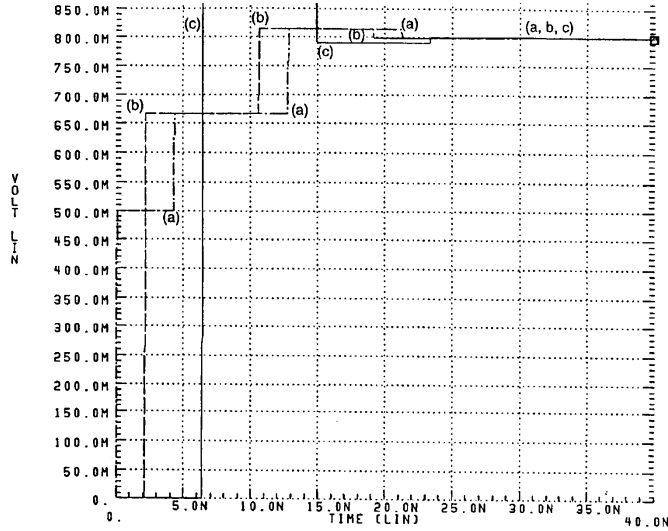


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## Compare previous results



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Figure 6.16 Voltage waveforms at (a) source, (b) junction of the two transmission line segments and (c) far end. See Fig. 6.15.

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## 2. Electromagnetic Waves

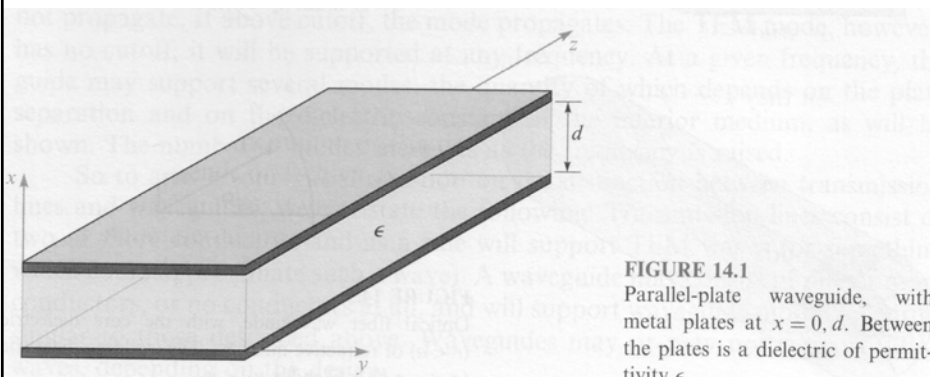


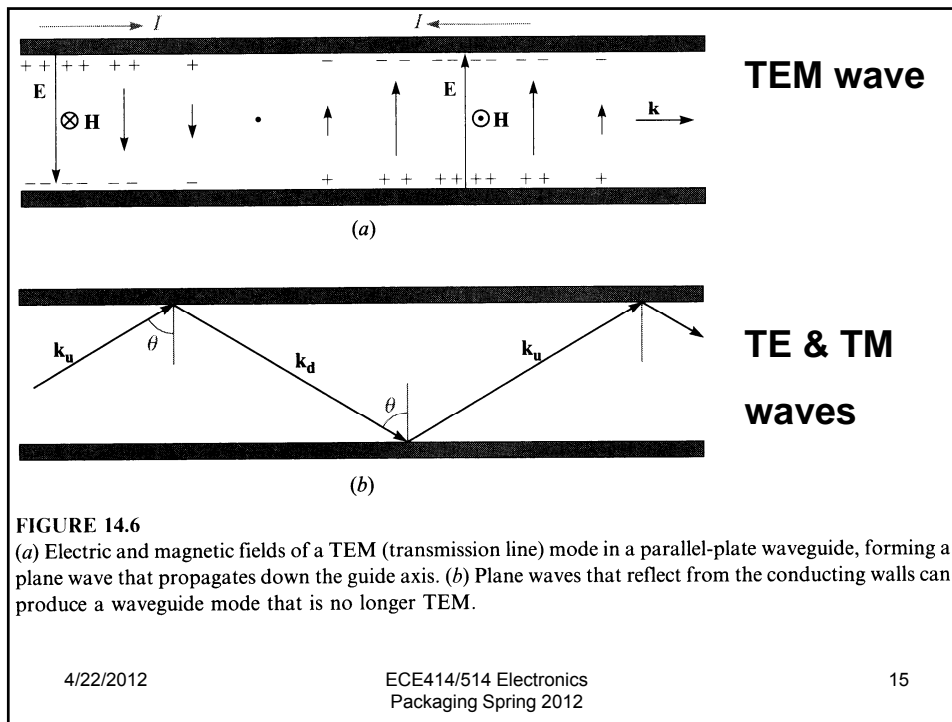
FIGURE 14.1  
Parallel-plate waveguide, with metal plates at  $x = 0, d$ . Between the plates is a dielectric of permittivity  $\epsilon$ .

### Parallel Plate Waveguides

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## Parallel Plate Waveguides

As for free space wave propagation:

$$\nabla^2 E_s = -k^2 E_s \quad \text{where } k = n\omega/c = \frac{\omega}{(c/n)}$$

Assume (TE) s-polarized waves  
 $n = \text{refractive index}$

$$= \frac{2\pi n}{\lambda} = \frac{2\pi}{(\lambda/n)}$$

For transverse electric waves:  $E_x = 0$   $E_y \neq 0$   $E_z = 0$

so  $\frac{\partial^2 E_{ys}}{\partial x^2} + \frac{\partial^2 E_{ys}}{\partial y^2} + \frac{\partial^2 E_{ys}}{\partial z^2} + k^2 E_{ys} = 0$

If waveguide width (y direction)  $\gg$  thickness (x direction)  
 and assuming propagation in the z direction

$$\frac{\partial^2 E_{ys}}{\partial y^2} = 0 \quad \text{and } z \text{ direction variation of form } \exp(-j\beta_m z)$$

then

$$E_{ys} = E_0 f_m(x) \exp(-j\beta_m z) \quad \text{for "mode number" } m$$

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Substitute  $E_{ys} = E_0 f_m(x) \exp -j\beta_m z$   
 into  $\frac{\partial^2 E_{ys}}{\partial x^2} + \frac{\partial^2 E_{ys}}{\partial z^2} + k^2 E_{ys} = 0$   
 gives  $\frac{d^2 f_m(x)}{dx^2} + (k^2 - \beta_m^2) f_m(x) = 0 \Rightarrow \frac{d^2 f_m(x)}{dx^2} + K_m^2 f_m(x) = 0$   
 where  $K_m^2 = k^2 - \beta_m^2$   
 with general solution  $f_m(x) = \cos K_m x + \sin K_m x$   
 Boundary conditions:  $E_y = 0$  at  $x = 0, d$  (due to conducting planes)  
 $\therefore f_m(x) = \sin \frac{m\pi}{d} x$   
 &  $E_{ys} = E_0 \sin \left( \frac{m\pi}{d} x \right) \exp -j\beta_m z$

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## Transverse Electric (TE) & Transverse Magnetic (TM) Waves

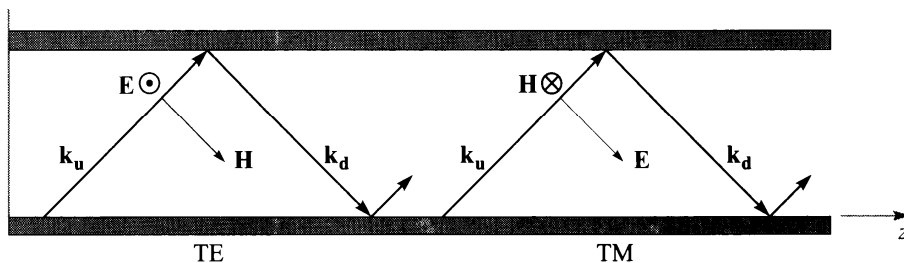


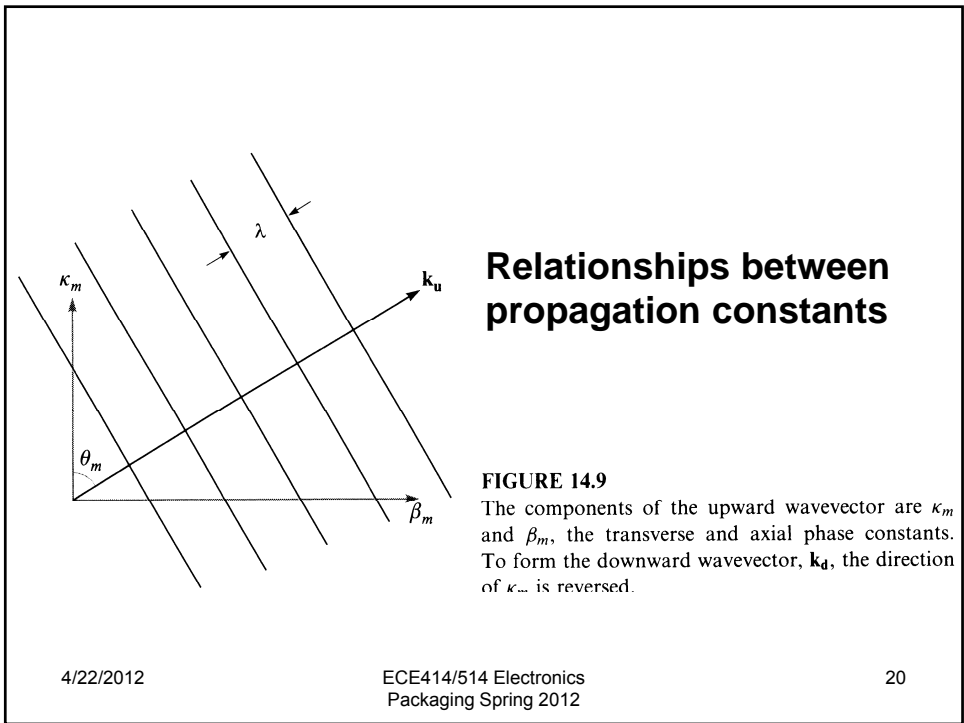
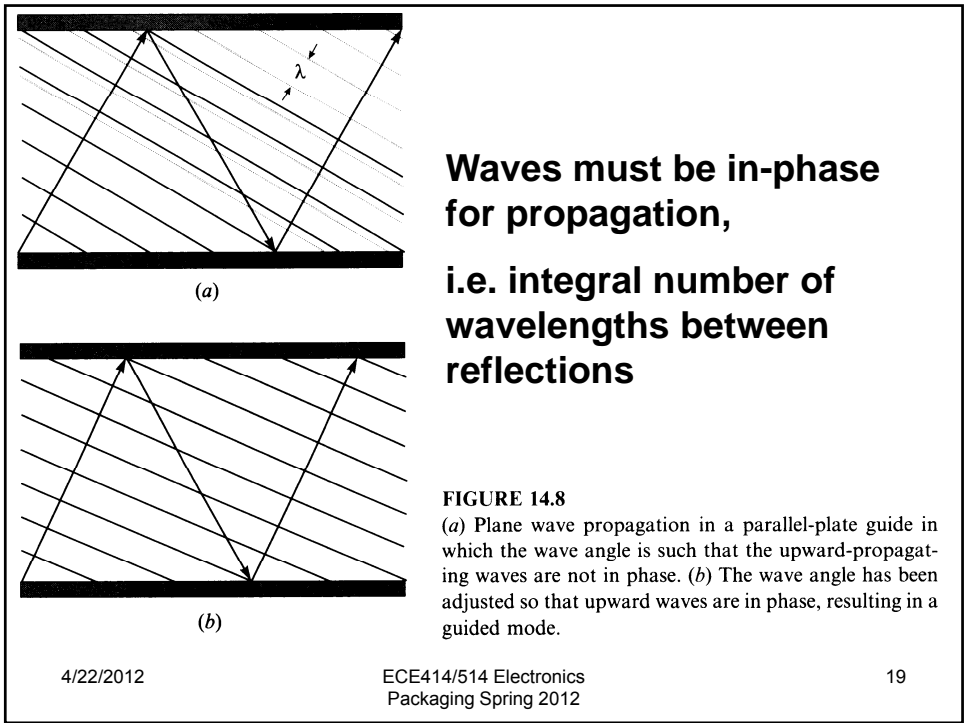
FIGURE 14.7

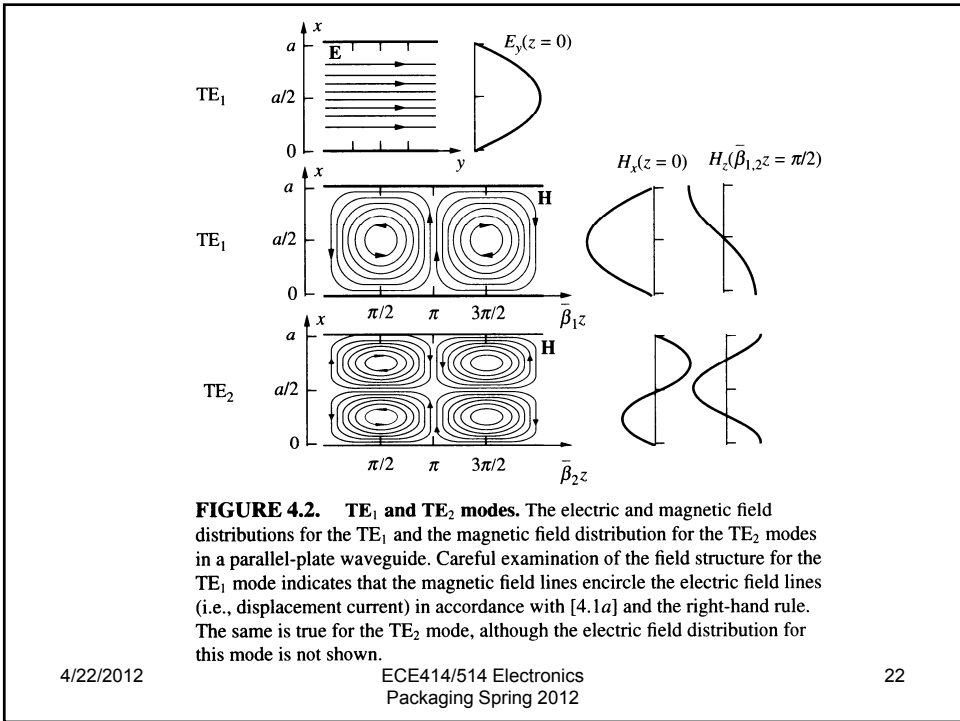
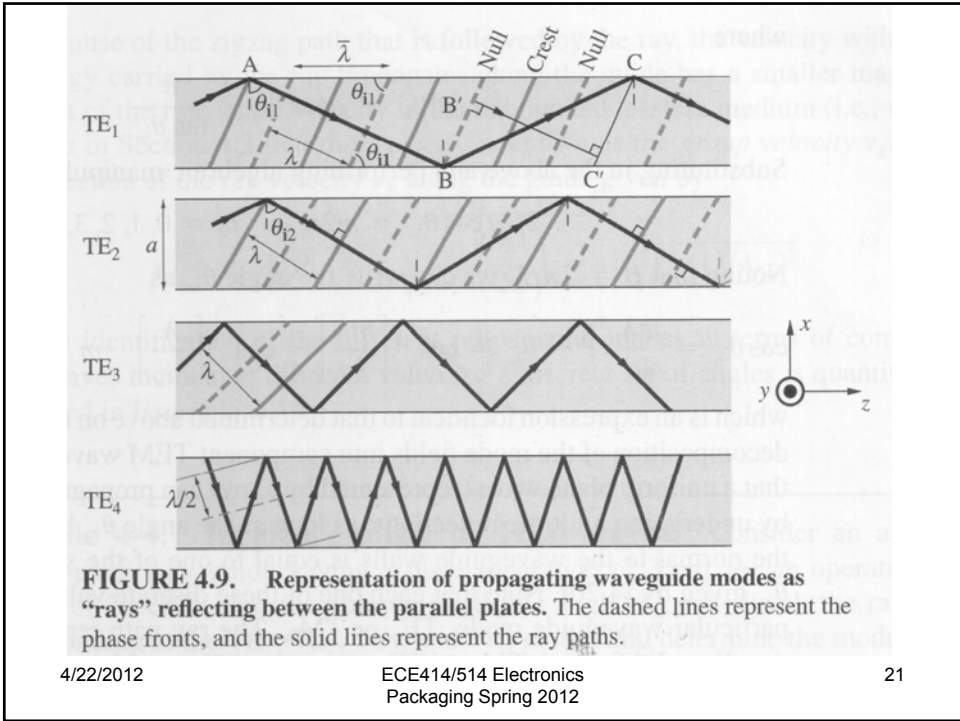
Plane wave representation of TE and TM modes in a parallel-plate guide.

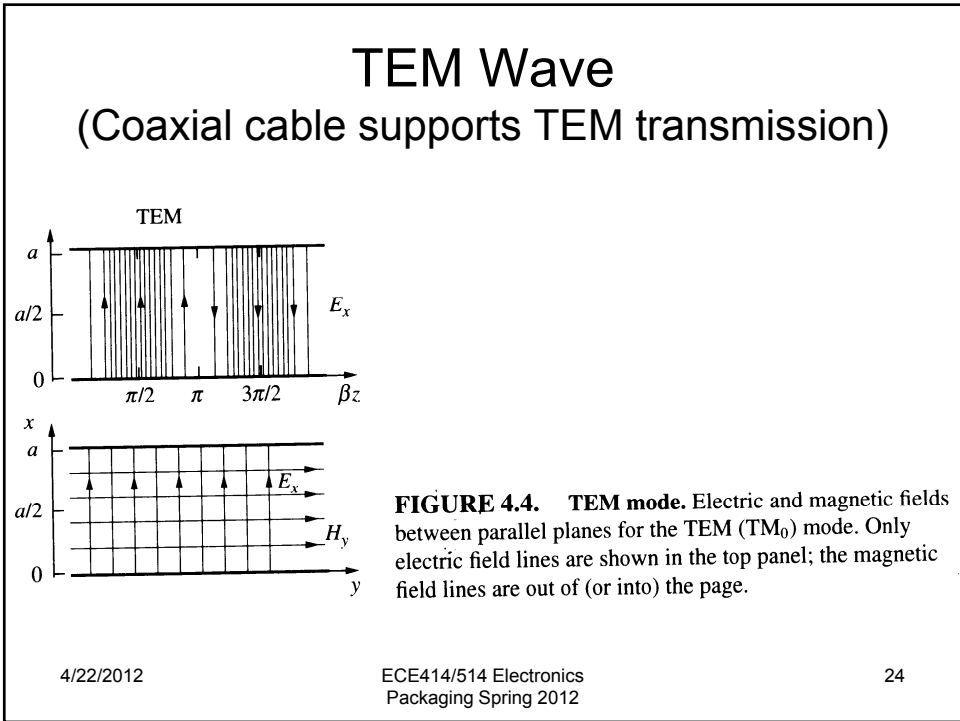
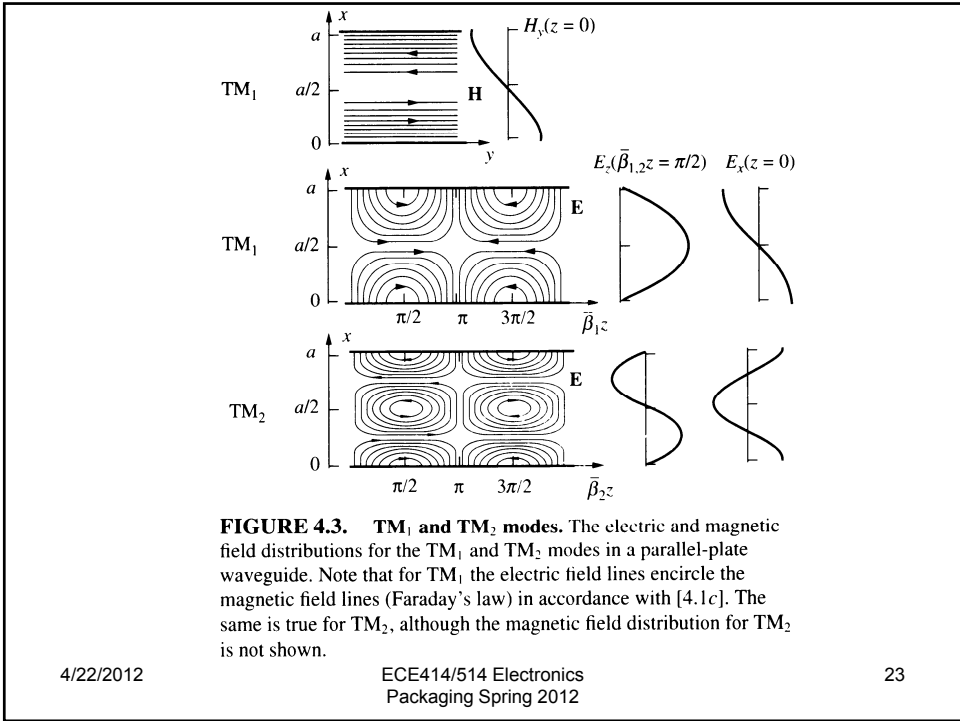
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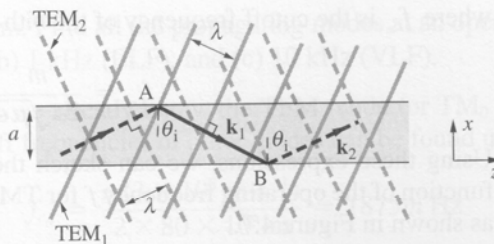
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## 2 TEMs $\rightarrow$ TE<sub>m</sub>



**FIGURE 4.8.** Two TEM waves forming a TE<sub>m</sub> wave in a parallel-plate waveguide. Waveguide modes represented as a superposition of two TEM waves. TEM<sub>1</sub> propagates in the direction  $\hat{k}_1 = \mathbf{k}_1/|\mathbf{k}_1|$  with surfaces of constant phase (i.e., phase fronts) indicated by solid lines. TEM<sub>2</sub> propagates in the direction  $\hat{k}_2 = \mathbf{k}_2/|\mathbf{k}_2|$ , with phase fronts shown in dashed lines. The same type of decomposition, and thus the same picture shown here, is also valid for the TM<sub>m</sub> modes.

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## TE and TM Cut-off Frequency

TE (or TM—"p-polarization") cut-off frequency for mode m

$$\omega_{cm} = \frac{m\pi c}{nd} \quad \text{i.e. when } d = \frac{m}{n} \frac{\lambda_{cm}}{2}$$

Total phase shift  $x=0$  to  $x=d$  to  $x=0 \Rightarrow 2k_m d = 2m\pi$   
for propagation (since reflective phase shifts at  
the conductor surfaces =  $2\pi$  (TE)  
or = 0 (TM))

i.e.  $k_m = m\pi/d$  for propagation

$$= k \cos \theta_m \quad \text{i.e. } \theta_m = \cos^{-1} \frac{m\pi}{kd} = \cos^{-1} \frac{m\pi c}{\omega nd} = \cos^{-1} \frac{m\lambda}{2nd}$$

$$\text{Propagation constant } \beta_m = \sqrt{k^2 - k_m^2} = k \sqrt{1 - \left(\frac{m\pi}{kd}\right)^2}$$

$$= k \sqrt{1 - \left(\frac{m\pi c}{\omega nd}\right)^2}$$

Cut off when  $\beta_m = 0$  i.e. when  $\omega_{cm} = \frac{m\pi c}{nd}$

$$\text{so write } \beta_m = \frac{n\omega}{c} \sqrt{1 - \left(\frac{\omega_{cm}}{\omega}\right)^2} \rightarrow \text{real (propagation)}$$

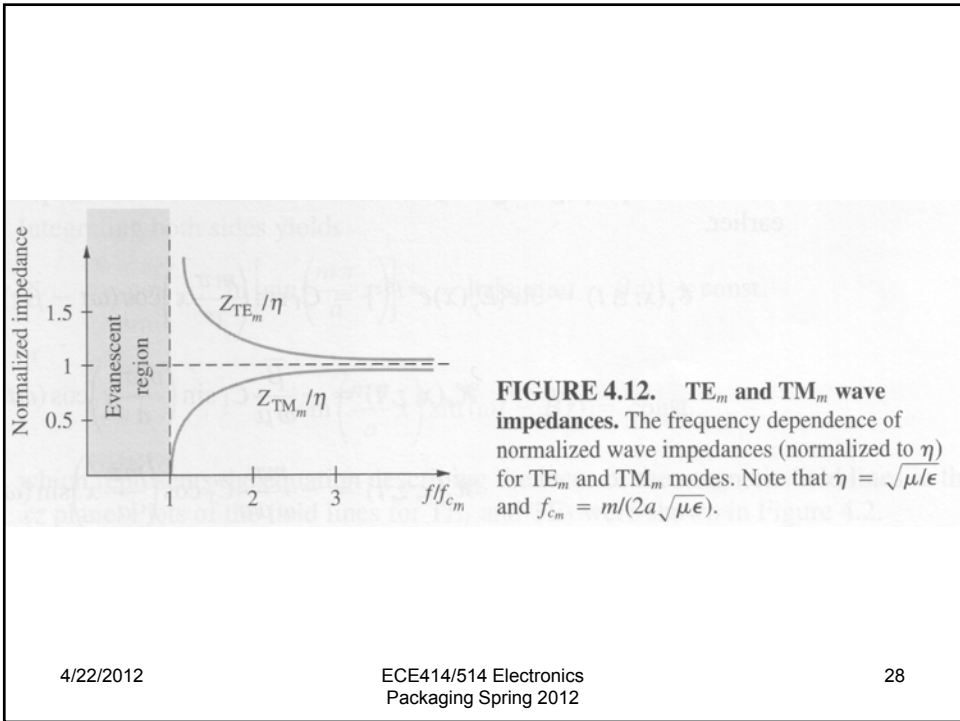
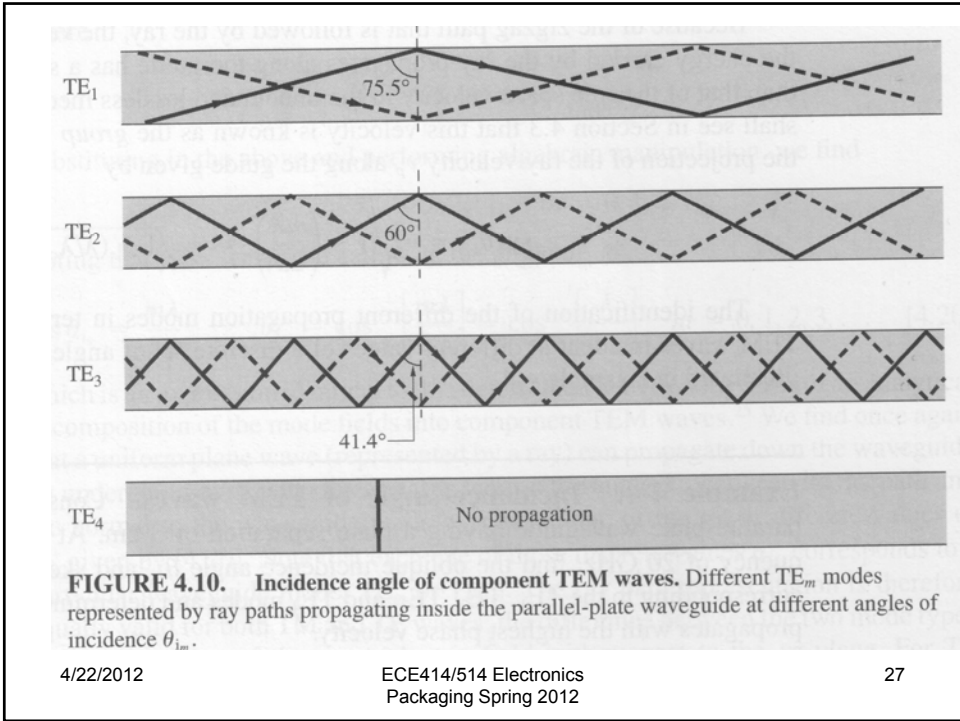
$$= \frac{2\pi n}{\lambda} \sqrt{1 - \left(\frac{\lambda}{\lambda_{cm}}\right)^2} \rightarrow \text{imaginary for } \omega < \omega_{cm}$$

(evanescent wave)

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# Microstrip transmission line

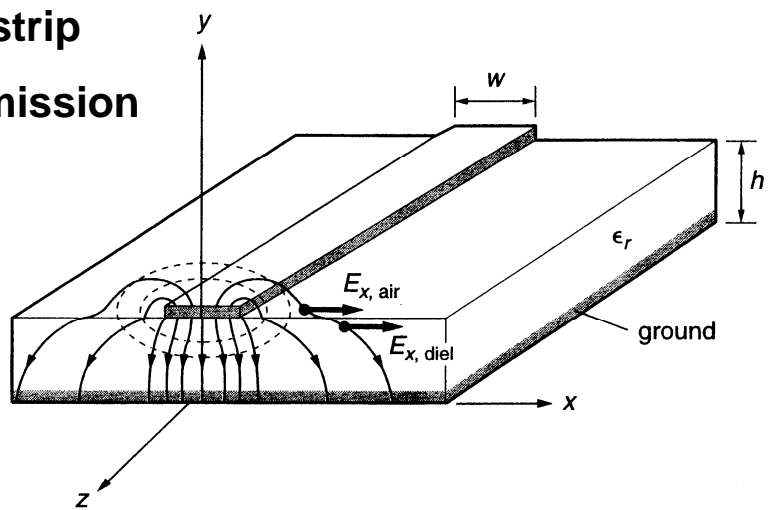


Figure 23.8 Sketch of a microstrip line. The electric field lines are sketched in solid line, and the magnetic field lines in dashed line.

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# Microstrip

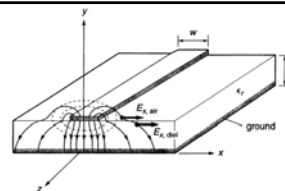


Figure 23.8 Sketch of a microstrip line. The electric field lines are sketched in solid line, and the magnetic field lines in dashed line.

At the boundary  $E_{x, \text{diel}} = E_{x, \text{air}}$  and  $H$  will be continuous (since no discontinuity in  $\mu$ ), so use

$$\vec{\nabla} \cdot \vec{E} = -\mu \frac{\partial}{\partial t} (\nabla \times \vec{H}) \Rightarrow \epsilon_r \frac{\partial H_{y, \text{air}}}{\partial y} - \frac{\partial H_{z, \text{diel}}}{\partial y} = (\epsilon_r - 1) \frac{\partial H_y}{\partial z}$$

RHS  $\neq 0$  ( $\epsilon_r > 1$  &  $H_y \neq 0$ )

$\therefore$  LHS  $\neq 0$  &  $\therefore H_z \neq 0$  & Similarly show  $E_z \neq 0$

$\therefore$  Propagating wave has non-zero  $H_z$  &  $E_z$

ie. must contain TE and TM modes.  $\Rightarrow$  "quasi-TEM"

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### 3. Electromagnetic Modeling

(Fang)

FE/FDTD simulations

Pulse transmission

Right-angled bend

Crosstalk (orthogonal lines)

Via effects

Experimental verification

Capacitor placement

Simulation demo

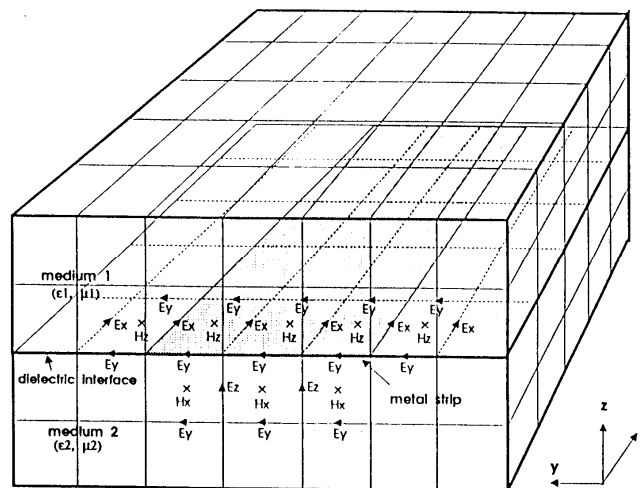
Note free demo software from [www.sonnetsoftware.com](http://www.sonnetsoftware.com)

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### Finite element mesh



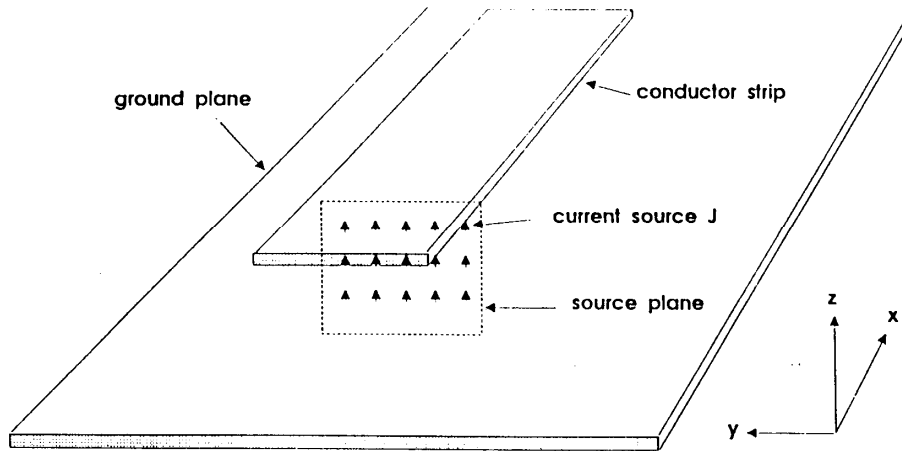
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## a. Current pulse excitation of line

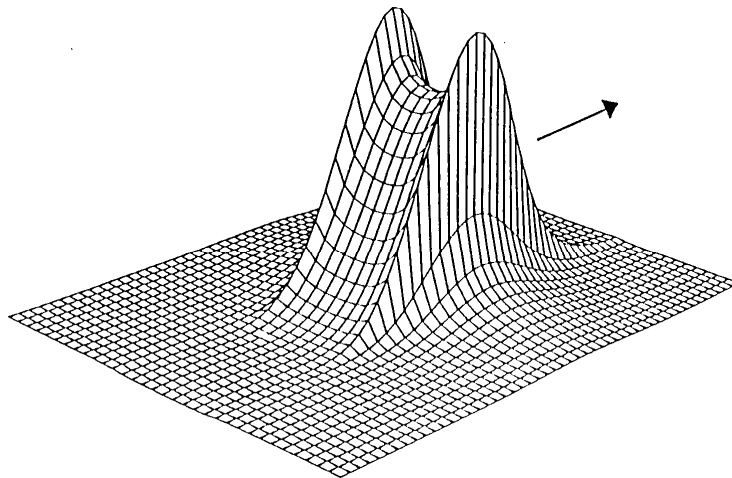


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## Electric field distribution on line

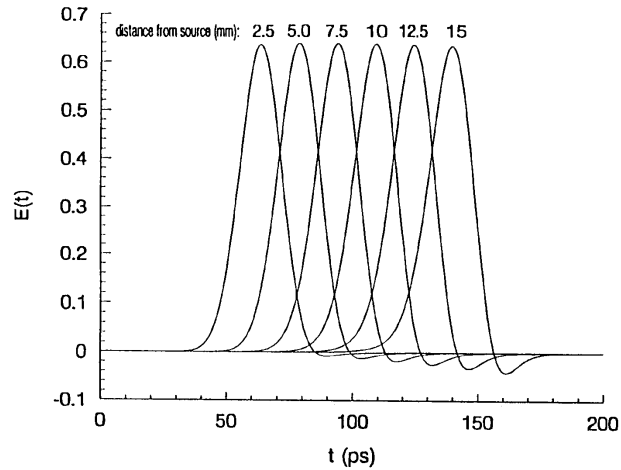


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## $E_z$ waveforms at different distances from the source at time $t$ .

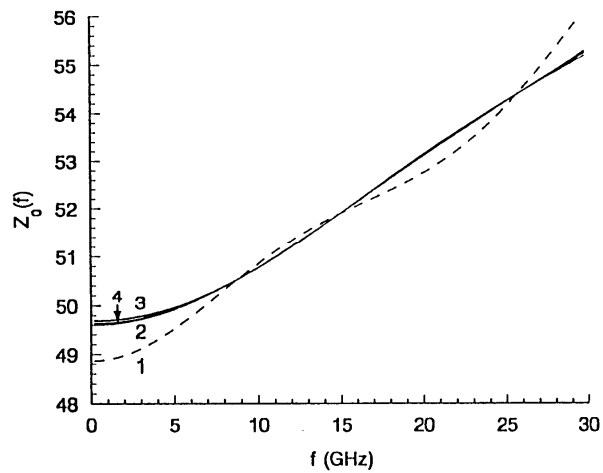


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## $Z_0(f)$ for different absorbing boundary conditions

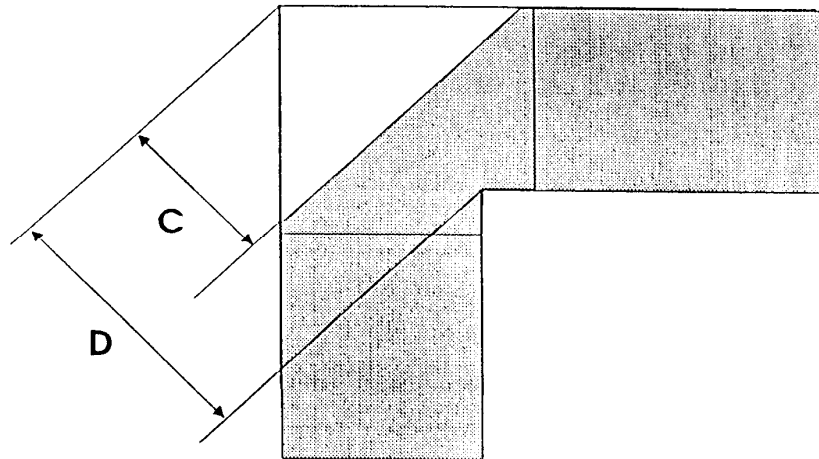


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## b. Chamfered right angle bend

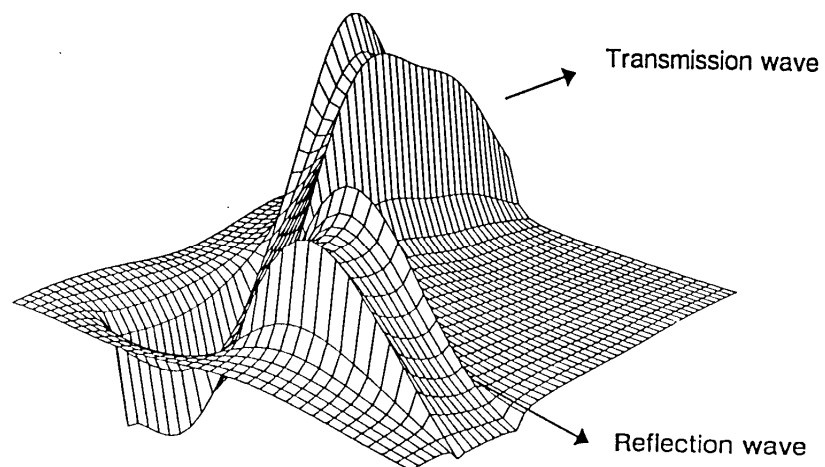


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## Pulse after reflection from corner

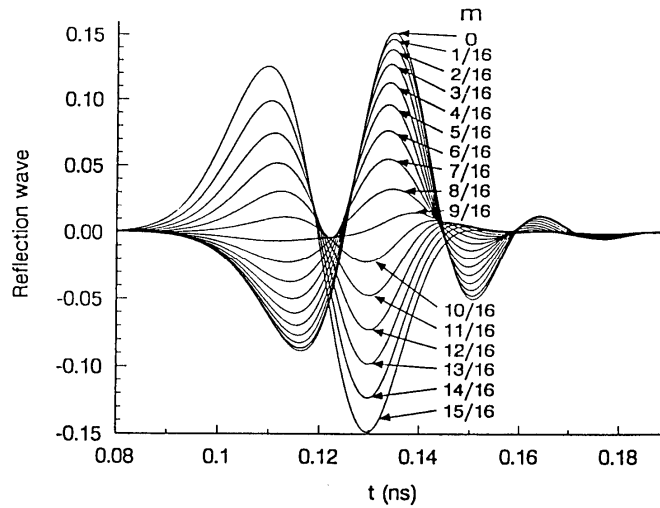


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## Reflected Gaussian pulse waveforms for varied chamfer factor $m$

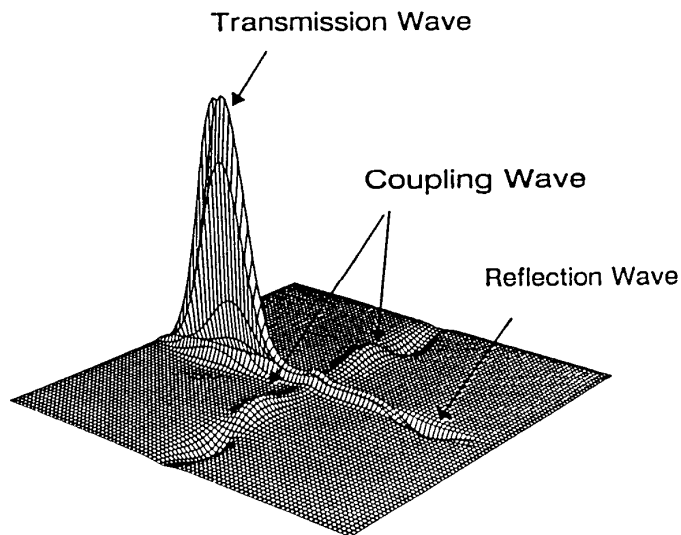


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## c. Orthogonal line crosstalk

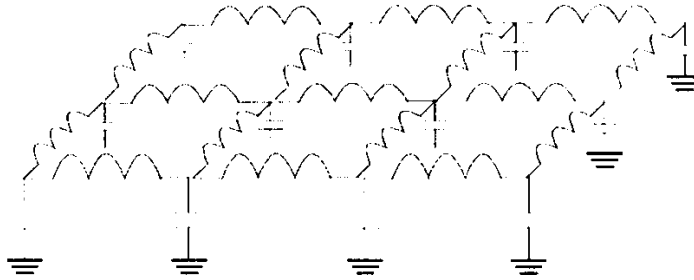


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## d. Signal/power ground coupling Capacitor-inductor mesh model



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## e. Simulation of multilayer packages (vias)

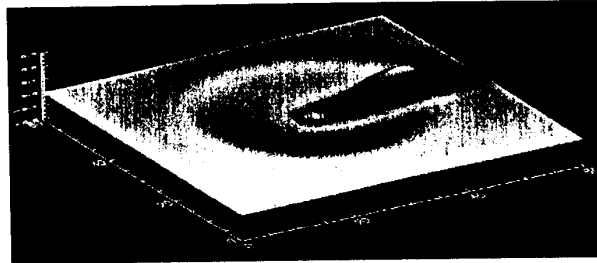
- EM fields decomposed into two parts:
  - Transmission line mode fields
    - Propagate along metal traces
    - Does not contribute to ground bounce
    - 3D fields
  - Parallel plate mode fields
    - Propagate between metal planes
    - Contributes to voltage power/ground bounce
    - 2D fields
- Simulations fast; then do interactions

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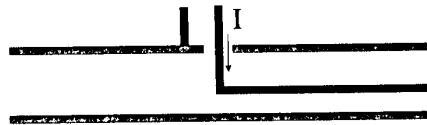
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## Electric fields between metal planes



- A strip line mode field and a parallel plate mode field can be identified

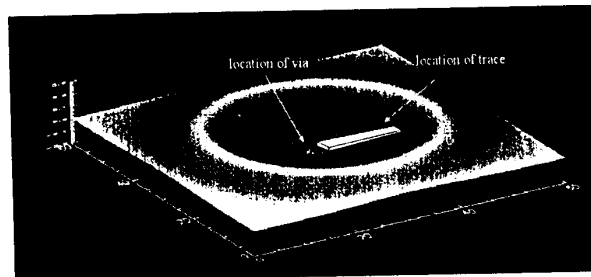


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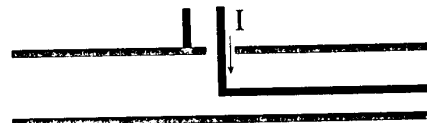
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## Voltage distribution across metal planes



- Parallel plate mode field propagates away from the via in the radial direction (not along the signal trace)



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## Performance comparison: CPU times

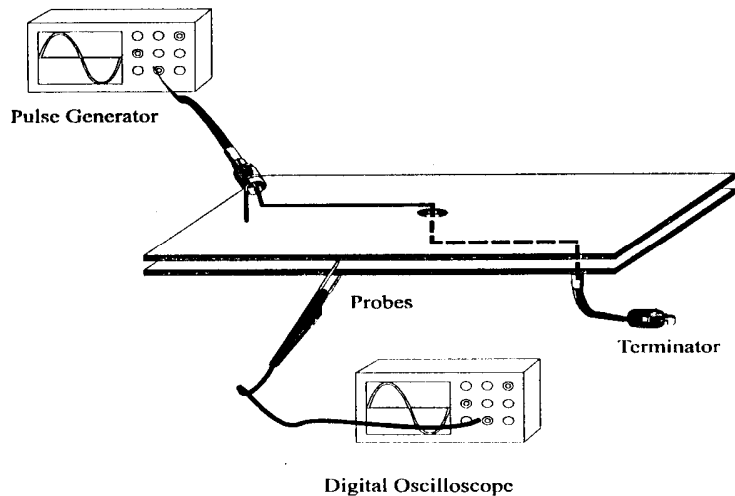
| Mesh density | ASTAP<br>IBM3090<br>mainframe | Separation<br>technique<br>IBM R/6000-350 | CPU<br>time<br>ratio |
|--------------|-------------------------------|---|----------------------|
| 30 H30       | 1min55.29s                    | 0.18sec                                   | 640                  |
| 42 H42       | 5min42.73s                    | 0.35sec                                   | 980                  |
| 60 H60       | 19min30.88s                   | 0.74sec                                   | 1582                 |

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## f. Experimental verification: set-up

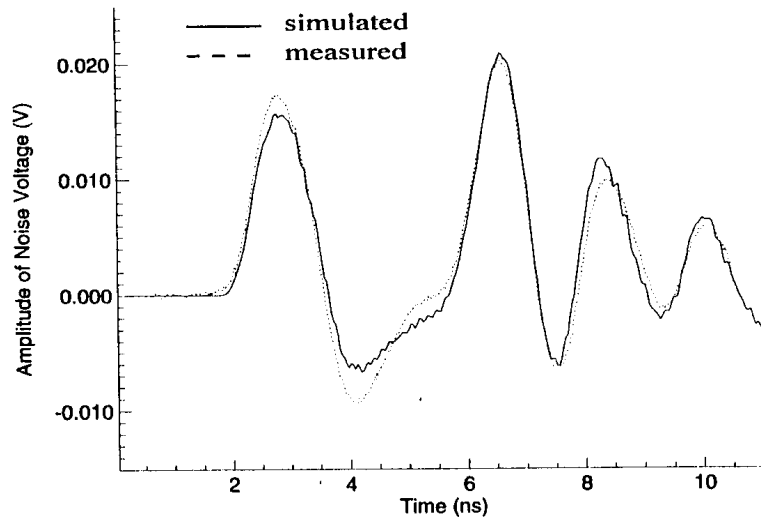


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## Experimental verification: results

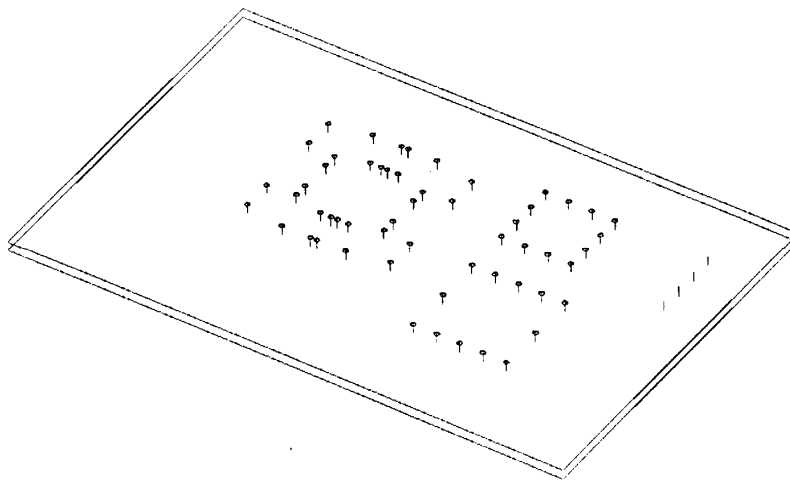


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## g. Delta-I & decoupling capacitor placement simulation



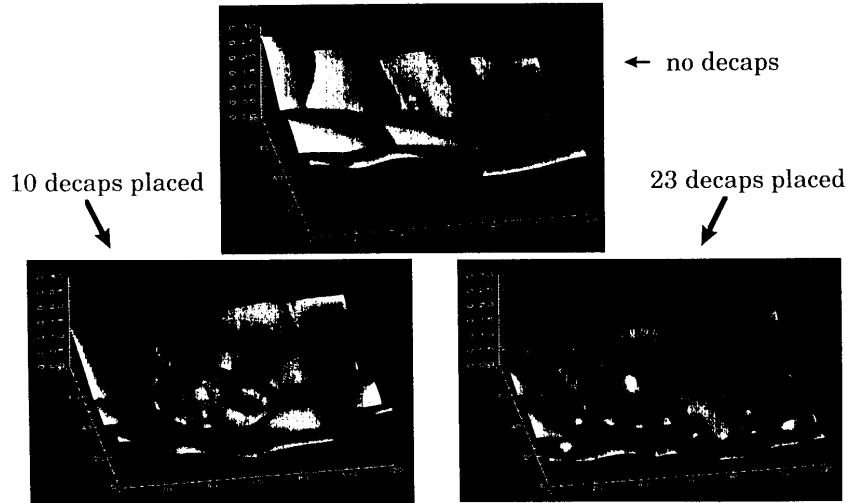
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# Voltage waveforms across board

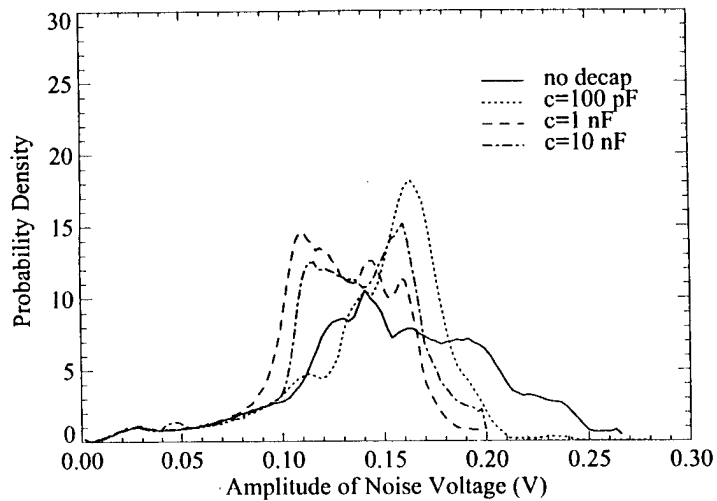


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# Evaluation of decoupling capacitor data



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